KEVET a YAGEO company

R53B, THB Grade IIIB, Class X2, 350 VAC, 125°C (Automotive Grade)

Overview

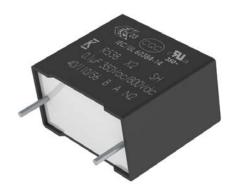
The R53B series is constructed of metallized polypropylene film encapsulated with self-extinguishing resin in a box of material that meets the requirements of UL 94 V-0. The R53B series is ideal for harsh environmental conditions and meets the demanding Automotive Electronics Council's AEC-Q200 qualification requirements.

Applications

For worldwide use in electromagnetic interference (EMI) suppression in across-the-line applications that require X2 safety classification. Intended for use in situations in which capacitor failure would not result in exposure to electric shock. Typical applications include connection in series with the mains, capacitive power supplies and energy meters, with special emphasis in automotive applications for severe ambient conditions such as On Board Chargers.

Benefits

- · Approvals: ENEC, UL, cUL, CQC
- X2 CLASS (IEC 60384-14)
- THB Grade IIIB: 85°C, 85% RH, 1,000 hours at 350 VAC/800 VDC acc. to IEC 60384-14
- Low Halogen Content according to JS709C
- Rated AC voltage: 350 VAC 50/60 Hz
- Rated DC Voltage: 800 VDC
- Recommended DC Voltage ≤ 1000 VDC
- Capacitance range: 0.068 20 μF
- Lead spacing: 15.0 52.5 mm
- Capacitance tolerance: ±20%, ±10%
- Climatic category 40/110/56, IEC 60068-1
- Tape & Reel in accordance with IEC 60286-2
- RoHS compliant and lead-free terminations
- Operating temperature range of -40°C to +125°C
- 100% screening factory test at 1,900 VDC
- · Self healing properties"
- Automotive (AEC-Q200) grade
- · Parallel and Series construction available



Part Number System

R53	В	I	3100	00	0	0	M	C-Spec
Series	Rated Voltage (VAC)	Lead Spacing (mm)	Capacitance Code (pF)	Packaging	Internal Use	Internal Use	Capacitance Tolerance	(Optional)
X2, Metallized Polypropylene	B = 350	I = 15.0 N = 22.5 R = 27.5 W = 37.5 Y = 52.5	The last three digits represent significant figures. The first digit specifies number of zeros to be added.	See Ordering Options Table	0 = Internal Parallel Construction S = Internal Series Construction	0 = Internal Use	K = ±10% M = ±20%	Blank = Standard V103 = 4 pins, S = 37.5 mm, S1 = 10.2 mm V104 = 4 pins, S = 37.5 mm, S1 = 20.3 mm

Built Into Tomorrow



Ordering Options Table

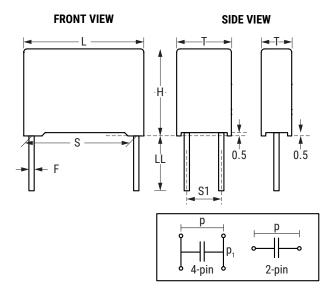
Lead Spacing Nominal (mm)	Type of Leads and Packaging	Lead Length (mm)	Lead and Packaging Code
	Standard Lead and Packaging Options		
	Bulk (Bag) – Short Leads	4 +2/-0	00
	Pizza Pack – Short Leads	4 +2/-0	BB
	Ammo Pack	$H_0 = 18.5 \pm 0.5$	DQ ¹
	Other Lead and Packaging Options		
15	Tape & Reel (Large Reel)	$H_0 = 18.5 \pm 0.5$	CK
10	Tape & Reel (Standard Reel)	$H_0 = 18.5 \pm 0.5$	GY ¹
22.5	Bulk (Bag)²– Short Leads	2.7 +0.5/-0	JA
22.5	Bulk (Bag)²– Short Leads	3.5 +0.5/-0	JB
	Bulk (Bag)²– Short Leads	4.0 +0.5/-0	JE
	Bulk (Bag)²– Short Leads	3.2 +0.3/-0.2	JH
	Bulk (Bag) – Long Leads	18 ±1	JM
	Bulk (Bag) – Long Leads	30 +5/-0	40
	Bulk (Bag) – Long Leads	25 +2/-1	50
	Standard Lead and Packaging Options		
	Bulk (Tray) – Short Leads	4 +2/-0	00
	Pizza Pack - Short Leads	4 +2/-0	BB
	Tape & Reel (Large Reel)	H ₀ = 18.5 ±0.5	CK ¹
	Other Lead and Packaging Options	110 1010 2010	5 1.
	Bulk (Tray) – Short Leads	2.7 +0.5/-0	JA
27.5	Bulk (Tray) – Short Leads	3.5 +0.5/-0	JB
	Bulk (Tray) – Short Leads	4.0 +0.5/-0	JE
	Bulk (Tray) – Short Leads	3.2 +0.3/-0.2	JH
	Bulk (Tray) – Long Leads	18 ±1	JM
	Bulk (Tray) – Long Leads	30 +5/-0	40
	Bulk (Tray) – Long Leads	25 +2/-1	50
	Standard Lead and Packaging Options Pizza Pack – Short Leads	4.27.0	00
	Other Lead and Packaging Options	4 +2/-0	00
		27.05/0	1.0
	Pizza Pack - Short Leads	2.7 +0.5/-0	JA
37.5	Pizza Pack - Short Leads	3.5 +0.5/-0	JB
	Pizza Pack – Short Leads Pizza Pack – Short Leads	4.0 +0.5/-0	JE JH
	Pizza Pack – Short Leads Pizza Pack – Long Leads	3.2 +0.3/-0.2	JM
	Pizza Pack – Long Leads	18 ±1	40
	Pizza Pack – Long Leads	30 +5/-0 25 +2/-1	50
	1 1220 1 dek Long Leaus	20 12/ 1	30
52.5	Standard Lead and Packaging Options		
J2.J	Pizza Pack – Short Leads	4 +2/-0	00

¹ Not for all sizes, see "Packaging Quantities" table.

 $^{^2}$ For lead spacing 22.5 case sizes \ge 8.5*17*26.5 the parts are packed in a Pizza box 335*320*34 mm



Dimensions - Millimeters



S		S1		Т		H		L		F	
Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance
15.0	±0.4	-	-	5.0	+0.3/-0.5	11.0	+0.3/-0.5	18.0	+0.5/-0.5	0.6	±0.05
15.0	±0.4	-	-	6.0	+0.3/-0.5	12.0	+0.3/-0.5	18.0	+0.5/-0.5	0.6	±0.05
15.0	±0.4	-	-	7.5	+0.3/-0.5	13.5	+0.3/-0.5	18.0	+0.5/-0.5	0.6	±0.05
15.0	±0.4	-	-	8.5	+0.3/-0.5	14.5	+0.3/-0.5	18.0	+0.5/-0.5	0.6	±0.05
15.0	±0.4	-	-	10.0	+0.3/-0.5	16.0	+0.3/-0.5	18.0	+0.5/-0.5	0.8	±0.05
15.0	±0.4	-	-	11.0	+0.3/-0.5	19.0	+0.3/-0.5	18.0	+0.5/-0.5	0.8	±0.05
22.5	±0.4	-	-	6.0	+0.3/-0.5	15.0	+0.3/-0.5	26.5	+0.5/-0.5	0.8	±0.05
22.5	±0.4	-	-	7.0	+0.3/-0.5	16.0	+0.3/-0.5	26.5	+0.5/-0.5	0.8	±0.05
22.5	±0.4	-	-	8.5	+0.3/-0.5	17.0	+0.3/-0.5	26.5	+0.5/-0.5	0.8	±0.05
22.5	±0.4	-	-	10.0	+0.3/-0.5	18.5	+0.3/-0.5	26.5	+0.5/-0.5	0.8	±0.05
22.5	±0.4	-	-	11.0	+0.3/-0.5	20.0	+0.3/-0.5	26.5	+0.5/-0.5	0.8	±0.05
22.5	±0.4	-	-	13.0	+0.3/-0.5	22.0	+0.3/-0.5	26.5	+0.5/-0.5	0.8	±0.05
27.5	±0.4	-	-	11.0	+0.3/-0.7	20.0	+0.3/-0.7	32.0	+0.5/-0.7	0.8	±0.05
27.5	±0.4	-	-	13.0	+0.3/-0.7	22.0	+0.3/-0.7	32.0	+0.5/-0.7	0.8	±0.05
27.5	±0.4	-	-	14.0	+0.3/-0.7	28.0	+0.3/-0.7	32.0	+0.5/-0.7	0.8	±0.05
27.5	±0.4	-	-	16.0	+0.3/-0.7	30.0	+0.3/-0.7	32.0	+0.5/-0.7	0.8	±0.05
27.5	±0.4	-	-	22.0	+0.3/-0.7	37.0	+0.3/-0.7	32.0	+0.5/-0.7	0.8	±0.05
37.5	±0.4	10.2(1)	±0.4	20.0	+0.3/-0.7	40.0	+0.3/-0.7	42.0	+0.5/-0.7	1.0	±0.05
37.5	±0.4	10.2(1)	±0.4	24.0	+0.3/-0.7	44.0	+0.3/-0.7	42.0	+0.5/-0.7	1.0	±0.05
37.5	±0.4	20.3(2)	±0.4	30.0	+0.3/-0.7	45.0	+0.3/-0.7	42.0	+0.5/-0.7	1.0	±0.05
52.5	±0.4	20.3(3)	±0.4	30.0	+1.2/-1.2	45.0	+1.2/-1.2	57.5	+1.2/-1.2	1.2	±0.05
52.5	±0.4	20.3(3)	±0.4	35.0	+1.2/-1.2	50.0	+1.2/-1.2	57.5	+1.2/-1.2	1.2	±0.05
	Note: See Ordering Options Table for lead length (LL/ H_0) options.										

⁽¹⁾ Standard = 2 pins, C-Spec V103 = 4 pins

⁽²⁾ Standard = 2 pins, C-Spec V104 = 4 pins

⁽³⁾ Standard = 4 pins, S1 = 20.3mm



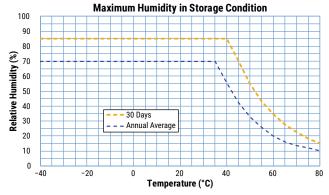
Performance Characteristics

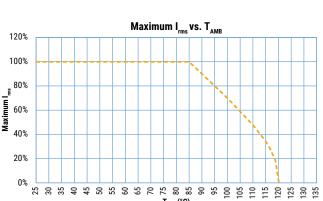
Dielectric	Polypropylene film									
Plates	Metal layer deposited by evaporation under vacuum									
Winding	Non-inductive type									
Leads	Tinned wire									
Protection		Plastic case, thermosetting resin filled. Box material is solvent resistant and flame retardant according to UL94.								
Related Documents	IEC 60384-14, EN 60384-									
Rated Voltage V _R	350 VAC (50/60 Hz) / 800									
Maximum Operational DC Voltage	≤ 1,000 VDC in parallel co									
Capacitance Range	0.068 −20 μF	(,,,,,								
Capacitance Values	-	asured at 1 kHz and +20 ±1°	`C							
Capacitance Tolerance	±10%, ±20%									
Temperature Range	-40°C to 125°C in paralle	l construction								
Climatic Category	40/110/56 IEC 60068-1									
	Construction	Temperature(°C)	Voltage (Vac)	Lifetime (khrs) [DeltaC = -20%)						
	2-Series	85	250	220						
	2-Series	85	305	220						
	2-Series	85	330	175						
	2-Series	85	350	135						
	Parallel	85	250	150						
	Parallel	85	305	150						
	Parallel	85	330	115						
Reliablity at AC Voltage	Parallel	85	350	70						
	1000 1000 1000 1000 1000 1000 1000 100	250 270 290 3	2 Series Parallel 310 330 350 37 ge [Vac]	0						
Reliablity at DC Voltage V _R	Operation life 100,000 ho	urs at 85°C , 1,000 hours at	125°C in parallel constructi	on						
, 3 · R		.,								

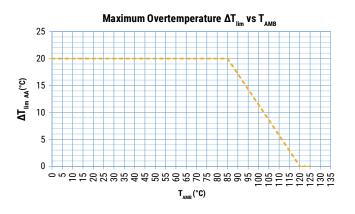


Performance Characteristics cont.

	Storage time: ≤ 24 months from the date marked on the label package						
	Average relative humidity per year ≤ 70%						
Storage Conditions	RH ≤ 85% for 30 days ran	domly distributed througho	ut the year				
	Dew is absent						
	Temperature: -40 to 80°C (see "Maximum Humidity in Storage Conditions" graph below)						
Approvals	ENEC, UL, cUL, CQC						
Dissipation Factor (tanδ) at 1 kHz	C ≤ 0.	47 μF	C > 0.47 μF				
`AT 25°C ±5°C	0.5	5%	0.3%				
Test Voltage Between Terminals	The voltage level is select All electrical characteristic	ry test is carried out at 1,900 ed to meet the requirements cs are checked after the test. EMET is not liable in such ca	in applicable equipment stan This test cannot be repeated				
	Measured at +25°C ±5°C, according to IEC 60384–2						
Insulation Resistance	Minimum Values Between Terminals						
	Voltage Charge	Voltage Charge Time	C ≤ 0.33 µF	C > 0.33 µF			
	100 VDC	1 minute	≥ 30,000 MΩ	≥ 10,000 MΩ • µF			







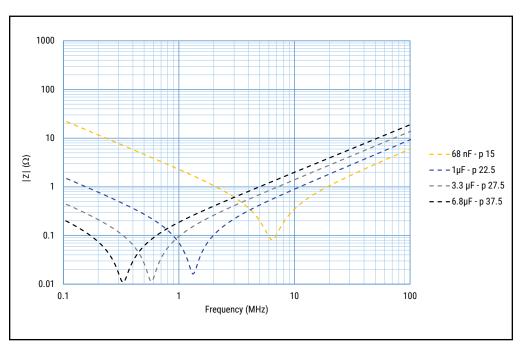
 $T_{\text{\tiny AMB}}$ is the maximum ambient temperature surrounding the capacitor or hottest contact point (e.g. tracks), whichever is higher, in the worst operation conditions in °C.



Qualification

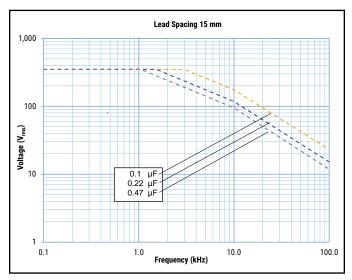
Automotive Grade products meet or exceed the requirements outlined by the Automotive Electronics Council. Details regarding test methods and conditions are referenced in document AEC-Q200, Stress Test Qualification for Passive Components. For additional information regarding the Automotive Electronics Council and AEC-Q200, please visit the website at www.aecouncil.com.

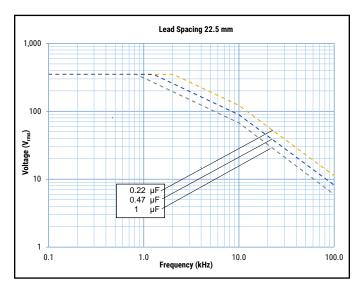
Impedance Graph

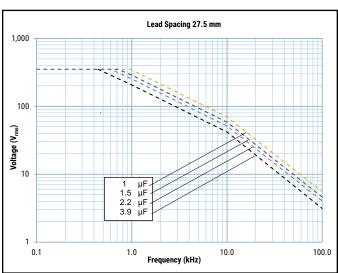


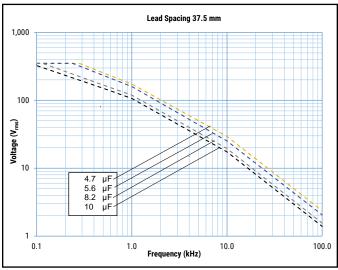


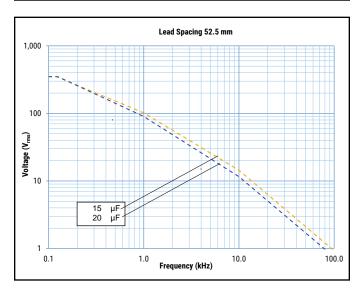
Maximum Voltage (V_{rms}) Versus Frequency (Sinusoidal Waveform/Th ≤ 85 °C)





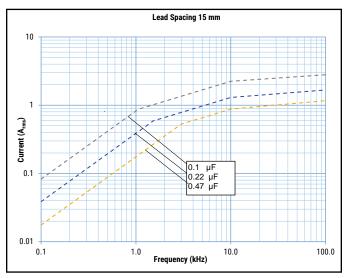


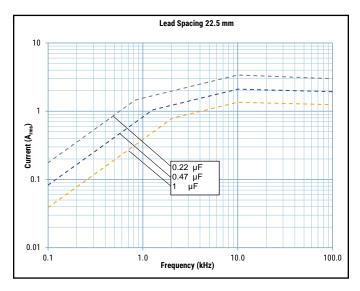


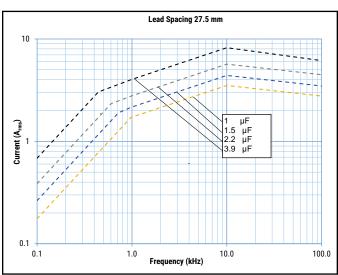


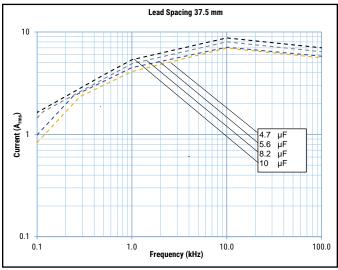


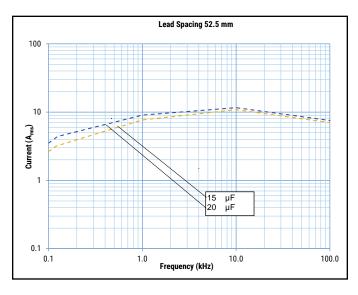
Maximum Current (I_{rms}) Versus Frequency (Sinusoidal Waveform/Th ≤ 85°C)













Environmental Test Data

Test	IEC Publication	Procedure				
Endurance	IEC 60384-14	$1.25 \times V_R$ VAC 50 Hz, once every hour increase to 1,000 VAC for 0.1 second, 1,000 hours at rated temperature (110°C)				
Endurance	IEC 60384-14	1.25 x V _{RDC} , 1,000 hours at rated temperature (110°C)				
Vibration	MIL-STD-202 Method 204	5 G for 20 minutes, 12 cycles each of 3 orientations. Use 8" X 5" PCB, 0.031" thick. 7 secure points on one 8" side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10 – 2,000 Hz.				
Mechanical Shock	MIL-STD-202 Method 213	Figure 1 of Method 213. Condition C				
Temperature Cycling	JESD22-Method JA-104	1,000 cycles (-40°C to 110°C) Note: Measurement at 24 ±4 hours afte test conclusion. 30 minute maximum dwell time at each temperature extreme. 1 minute maximum transition time.				
Active Flammability	IEC 60384-14	V_R + 20 surge pulses at 2.5 kV (pulse every 5 seconds)				
Passive Flammability	IEC 60384-14	IEC 60384-1, IEC 60695-11-5 Needle flame test				
Biased Humidity	According to Grade IIIB (Certification pending) For Parallel and Series construction	85°C/85% RH and 350 VAC, 1,000 hours Capacitance change (Δ C/C): \leq 10% Dissipation factor change (Δ tan δ): \leq 150 * 10 ⁻⁴ (at 1 kHz for Cap > 1 μF) Dissipation factor change (Δ tan δ): \leq 240 * 10 ⁻⁴ (at 10 kHz) for Cap \leq 1 μF IR \geq 50% of initial limit or minimum 200 M Ω				
ыаѕей пиннику	According to Grade IIIB (Certification pending) For Parallel construction only	85°C/85% RH and 350 VAC, 1,000 hours Capacitance change (Δ C/C): \leq 10% Dissipation factor change (Δ tan δ): \leq 150 * 10 ⁻⁴ (at 1 kHz for Cap > 1 μF) Dissipation factor change (Δ tan δ): \leq 240 * 10 ⁻⁴ (at 10 kHz) for Cap \leq 1 μF IR \geq 50% of initial limit or minimum 200 M Ω				

Approvals

Certification Body	Mark	Specification	File Number
IMQ S-p.A.		EN/IEC 60384-14	CA08.00236
UL	c FN° us	UL 60384-14 and CAN/CSA E60384-14 (350 VAC)	E97797
CQC	cec	IEC 60384-14	Pending



Environmental Compliance

All KEMET EMI capacitors are RoHS compliant.





Table 1 – Ratings & Part Number Reference

Capacitance	Dimensions in mm			Lead Spacing	dV/dt	KEMET	Legacy Part
Value (μF)	Т	Н	L	(S)	(V/µs)	Part Number	Number
0.068	5.0	11.0	18.0	15	400	53BI2680(1)00(2)	R53BI2680(1)00(2)
0.1	6.0	12.0	18.0	15	400	53BI3100(1)00(2)	R53BI3100(1)00(2)
0.15	7.5	13.5	18.0	15	400	53BI3150(1)00(2)	R53BI3150(1)00(2)
0.22	8.5	14.5	18.0	15	400	53BI3220(1)00(2)	R53BI3220(1)00(2)
0.33	10.0	16.0	18.0	15	400	53BI3330(1)00(2)	R53BI3330(1)00(2)
0.39	11.0	19.0	18.0	15	400	53BI3390(1)00(2)	R53BI3390(1)00(2)
0.47	11.0	19.0	18.0	15	400	53BI3470(1)00(2)	R53BI3470(1)00(2)
0.22	6.0	15.0	26.5	22.5	200	53BN3220(1)00(2)	R53BN3220(1)00(2)
0.33	7.0	16.0	26.5	22.5	200	53BN3330(1)00(2)	R53BN3330(1)00(2)
0.47	8.5	17.0	26.5	22.5	200	53BN3470(1)00(2)	R53BN3470(1)00(2)
0.56	10.0	18.5	26.5	22.5	200	53BN3560(1)00(2)	R53BN3560(1)00(2)
0.68	11.0	20.0	26.5	22.5	200	53BN3680(1)00(2)	R53BN3680(1)00(2)
1	13.0	22.0	26.5	22.5	200	53BN4100(1)00(2)	R53BN4100(1)00(2)
0.82	11.0	20.0	32.0	27.5	150	53BR3820(1)00(2)	R53BR3820(1)00(2)
1	13.0	22.0	32.0	27.5	150	53BR4100(1)00(2)	R53BR4100(1)00(2)
1.2	13.0	22.0	32.0	27.5	150	53BR4120(1)00(2)	R53BR4120(1)00(2)
1.5	13.0	25.0	32.0	27.5	150	53BR4150(1)00(2)	R53BR4150(1)00(2)
1.8	14.0	28.0	32.0	27.5	150	53BR4180(1)00(2)	R53BR4180(1)00(2)
2.2	16.0	30.0	32.0	27.5	150	53BR4220(1)00(2)	R53BR4220(1)00(2)
3.3	22.0	37.0	32.0	27.5	150	53BR4330(1)00(2)	R53BR4330(1)00(2)
3.9	22.0	37.0	32.0	27.5	150	53BR4390(1)00(2)	R53BR4390(1)00(2)
4.7	20.0	40.0	42.0	37.5	100	53BW4470(1)00(2)	R53BW4470(1)00(2)
5.6	20.0	40.0	42.0	37.5	100	53BW4560(1)00(2)	R53BW4560(1)00(2)
6.8	24.0	44.0	42.0	37.5	100	53BW4680(1)00(2)	R53BW4680(1)00(2)
8.2	24.0	44.0	42.0	37.5	100	53BW4820(1)00(2)	R53BW4820(1)00(2)
10	30.0	45.0	42.0	37.5	100	53BW5100(1)00(2)	R53BW5100(1)00(2)
15	30.0	45.0	57.5	52.5	50	53BY5150(1)00(2)	R53BY5150(1)00(2)
18	35.0	50.0	57.5	52.5	50	53BY5180(1)00(2)	R53BY5180(1)00(2)
20	35.0	50.0	57.5	52.5	50	53BY5200(1)00(2)	R53BY5200(1)00(2)
Capacitance Value (µF)	T (mm)	H (mm)	L (mm)	Lead Spacing (S)	dV/dt (V/μs)	KEMET Part Number	Legacy Part Number

⁽¹⁾ Insert lead and packaging code. See Ordering Options Table for available options.

⁽²⁾ $M = \pm 20\%$, $K = \pm 10\%$



Soldering Process

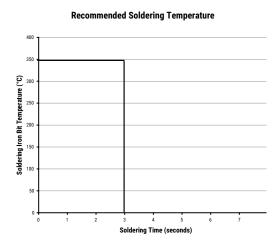
The implementation of the RoHS directive has resulted in the selection of SnAuCu (SAC) alloys or SnCu alloys as primary solder material. This has increased the liquidus temperature from 183° C for SnPb eutectic alloys to $217 - 221^{\circ}$ C for the new alloys. As a result, the heat stress to the components, even in wave soldering, has increased considerably due to higher preheat and wave temperatures. Polypropylene capacitors are especially sensitive to heat (the melting point of polypropylene is $160 - 170^{\circ}$ C). Wave soldering can be destructive, especially for mechanically small polypropylene capacitors (with lead spacing of 5 - 15 mm). Great care must be taken during soldering. The recommended solder profiles from KEMET should be used. Consult KEMET with any questions. In general, the wave soldering curve from IEC Publication 61760-1 Edition 2 serves as a solid quideline for successful soldering. See Figure 1.

Reflow soldering is not recommended for through-hole film capacitors. Exposing capacitors to a soldering profile in excess of the above-recommended limits may result to degradation of or permanent damage to the capacitors.

Do not place the polypropylene capacitor through an adhesive curing oven to cure resin for surface mount components. Insert through-hole parts after curing surface mount parts. Consult KEMET to discuss the actual temperature profile in the oven, if through-hole components must pass through the adhesive curing process. A maximum two soldering cycles is recommended. Allow time for the capacitor surface temperature to return to normal temperature before performing the second soldering cycle.

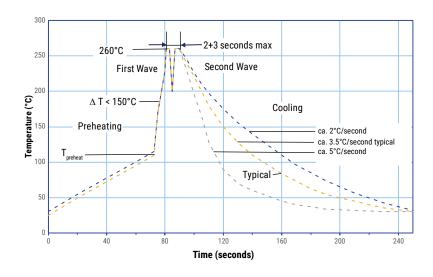
Manual Soldering Recommendations

Following is the recommendation for manual soldering with a soldering iron.



The soldering iron tip temperature should be set at 350°C (+10°C maximum), with the soldering duration not to exceed more than 3 seconds.

Wave Soldering Recommendations





Soldering Process cont.

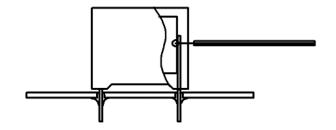
Wave Soldering Recommendations cont.

1. The table indicates the maximum set-up temperature of the soldering process.

Dielectric		mum heat erature	Maximum Peak Soldering Temperature		
Film Material	Capacitor Pitch ≤ 15 mm	Capacitor Pitch > 15 mm	Capacitor Pitch ≤ 15 mm	Capacitor Pitch > 15 mm	
Polyester	130°C	130°C	270°C	270°C	
Polypropylene	125°C	130°C	260°C	270°C	
Paper	130°C	140°C	270°C	270°C	
Polyphenylene Sulphide	150°C	160°C	270°C	270°C	

2. The maximum temperature measured inside the capacitor: set the temperature so that the maximum temperature inside the element is below the limit.

Dielectric Film Material	Maximum Temperature Measured Inside the Element		
Polyester	160°C		
Polypropylene	125°C		
Paper	160°C		
Polyphenylene Sulphide	160°C		



Temperature monitored inside the capacitor.

Selective Soldering Recommendations

Selective dip soldering is a variation of reflow soldering. In this method, the printed circuit board with through-hole components to be soldered is preheated and transported over the solder bath as it is in normal flow soldering, without touching the solder. When the board is over the bath, it is stopped. Pre-designed solder pots are lifted from the bath with molten solder, only at the places of the selected components, and pressed against the lower surface of the board to solder the components.

The temperature profile for selective soldering is similar to the double wave flow soldering outlined in this document. **However, instead of two baths, there is only one with a time from 3 – 10 seconds.** In selective soldering, the risk of overheating is greater than in double wave flow soldering, and great care must be taken so that the parts do not overheat.



Mounting

Resistance to Vibration and Mechanical Shock

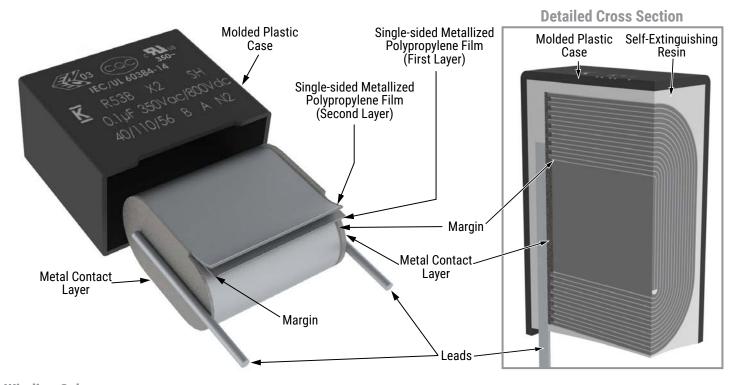
	AEC-Q200 Mechanical Stress Tests:							
Mechanical Shock	MIL-SDT-202 Method 213	Test condition C Peak value 100 g, duration 6 ms, half-sine-wave (see MIL-HDBK for details)						
Vibration	MIL-SDT-202 Method 204	5 G for 20 minutes, 12 cycles each of 3 orientations Use 8"X5" PCB, 0.031" thick. 7 secure points on one 8" side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10 – 2,000 Hz.						

The capacitors are designed for PCB mounting.

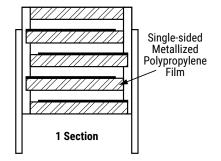
The stand-off pipes must be in good contact with the printed circuit board.

The capacitor body has to be properly fixed (e.g. clamped or glued).

Construction

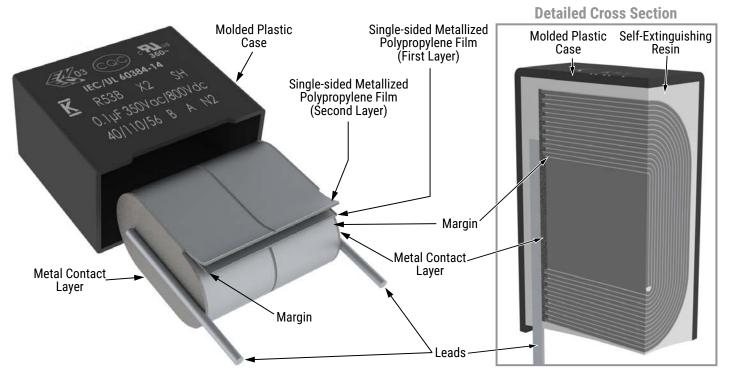


Winding Scheme

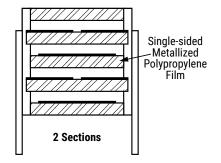




Construction cont.



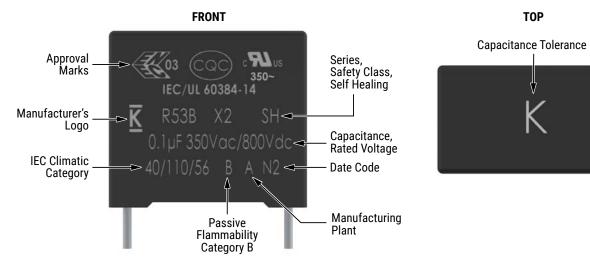
Winding Scheme



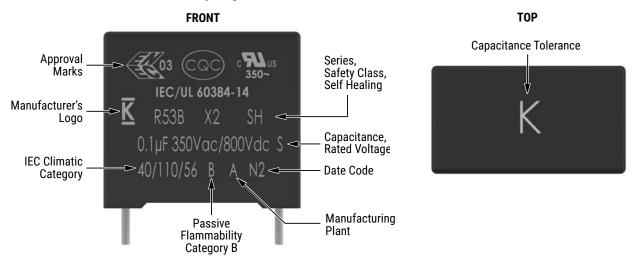


Marking

Parallel Construction Part Numbers: Lead Spacing 15 mm, 22.5 mm, and 27.5 mm



Series Construction Part Numbers: Lead Spacing 15 mm, 22.5 mm, and 27.5 mm

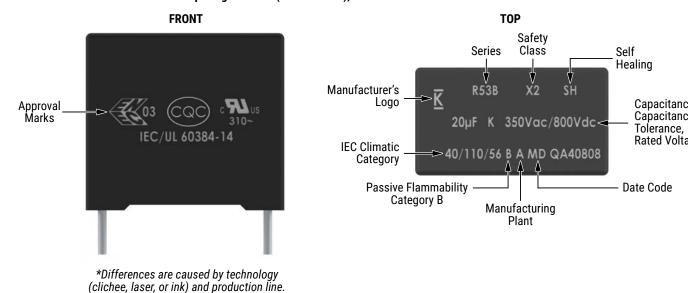


Manufacturing Date Code (IEC-60062)									
Year	Code	Year	Code	Month	Code	Month	Code		
2010	A	2020	М	January	1	July	7		
2011	В	2021	N	February	2	August	8		
2012	С	2022	Р	March	3	September	9		
2013	D	2023	R	April	4	October	0		
2014	Е	2024	S	May	5	November	N		
2015	F	2025	Т	June	6	December	D		
2016	Н	2026	U						
2017	J	2027	V						
2018	K	2028	W						
2019	L	2029	X						

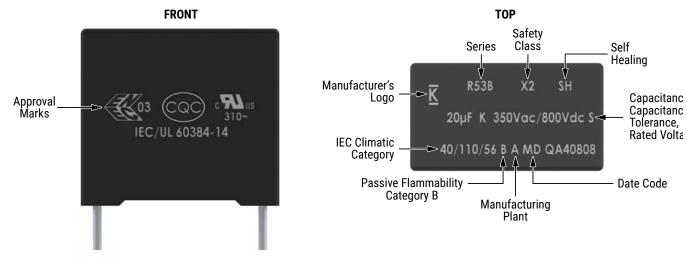


Marking cont.

Parallel Construction Part Numbers: Lead Spacing 27.5 mm (alternatives*), 37.5 mm and 52.5 mm



Series Construction Part Numbers: Lead Spacing 27.5 mm (alternatives*), 37.5 mm and 52.5 mm



*Differences are caused by technology (clichee, laser, or ink) and production line.

Manufacturing Date Code (IEC-60062)							
Year	Code	Year	Code	Month	Code	Month	Code
2010	A	2020	М	January	1	July	7
2011	В	2021	N	February	2	August	8
2012	С	2022	Р	March	3	September	9
2013	D	2023	R	April	4	October	0
2014	E	2024	S	May	5	November	N
2015	F	2025	Т	June	6	December	D
2016	Н	2026	U				
2017	J	2027	V				
2018	K	2028	W				
2019	L	2029	X				



Packaging Quantities

Lead Spacing (mm)	Thickness (mm)	Height (mm)	Length (mm)	Bulk Short Leads		ılk Leads	Standard Reel ø 355 mm	Large Reel ø 500 mm	Ammo Taped	Pizza
Lead and Packaging Code:			00 - JA - JB JE - JH	JM	40 - 50	GY	СК	DQ	ВВ	
	5	11	18	2,000	1,250	1,000	600	1,250	800	1,122
	6	12	18	1,750	1,000	900	500	1,000	680	935
15	7.5	13.5	18	1,000	800	700	350	800	500	748
15	8.5	14.5	18	1,000	650	500	300	700	440	663
	10	16	18	750	550	500	270	600	380	561
	11	19	18	450	400	350	-	500	340	510
	6	15	26.5	805	450	500	-	700	464	660
22.5	7	16	26.5	700	450	500	-	550	380	564
	8.5	17	26.5	468	350	300	-	450	280	468
	10	18.5	26.5	396	350	300	-	350	235	396
	11	20	26.5	360	200	250	-	350	217	360
	13	22	26.5	300	150	200	-	300	-	300
	11	20	20	FCO	226	226		350		200
	11	20	32	560	336	336	-		-	300
	13	22	32	480	288	288	-	300	-	250
27.5	13	25	32	480	288	288	-	-	-	
	14	28	32	352	176	176	-	-	-	230
	16	30	32	288	144	144	-	-	-	200
	22	37	32	168	112	112	-	-	-	150
37.5	20	40	42	_	_	_	-	-	_	58
	24	44	42	_	_	-	-	-	-	44
	30	45	42	-	-	-	-	-	-	36
52.5	30	45	57.5	-	-	-	-	-	-	27
02.0	35	50	57.5	-	-	-	-	-	-	23



Lead Taping & Packaging (IEC 60286-2)

Figure 1 - Lead Spacing 15 mm

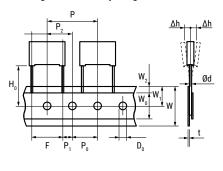
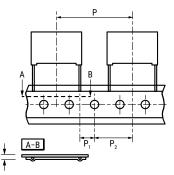


Figure 2 - Lead Spacing 22.5 & 27.5 mm



Taping Specification

			Dimensio	ons (mm)				
Description	Symbol		Lead Space		Tolerance			
		15.0	22.5	27.5	Tolerance			
Lead wire diameter	d	0.6 - 0.8	0.8	0.8	±0.05			
Taping lead space	Р	25.4	38.1	38.1	±1			
Feed hole lead space *	P ₀	12.7	12.7	12.7	±0.2 **			
Centering of the lead wire	P ₁	5.2	7.8	5.3	±0.7			
Centering of the body	P ₂	12.7	19.05	19.05	±1.3			
Lead spacing ***	F	15.0	22.5	27.5	+0.6/-0.1			
Component alignment	Δh	0	0	0	±2			
Component deviation	Δр	0	0	0	±1			
Height of component from tape center	H ₀ ****	18.5	18.5	18.5	±0.5			
Carrier tape width	W	18	18	18	+1/-0.5			
Hold down tape width	W _o	10	10	10	Minimum			
Hole position	W ₁	9	9	9	±0.5			
Hold down tape position	W ₂	3	3	3	Maximum			
Feed hole diameter	D ₀	4	4	4	±0.2			
Total Tape thickness	t	0.7	0.7	0.7	±0.2			

^{*} Available also 15 mm.

^{**} Maximum 1 mm on 20 lead spacing.

^{*** 15} mm and 10 mm taped to 7.5 mm (crimped leads) available upon request.

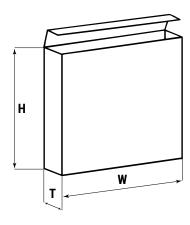
^{****} H_0 = 16.5 mm is available upon request.



Lead Taping & Packaging (IEC 60286-2) cont.

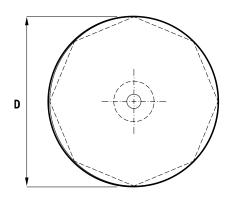
Ammo Specifications

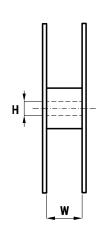
Dimensions (mm)						
H W T						
360	340	59				



Reel Specifications

Reel Size	Dimensions (mm)				
Reel Size	D	Н	W		
Standard	355	30	EE Mavimum		
Large	500	25	55 Maximum		







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